## **<b>&TDK** Multilayer Ceramic Chip Capacitors

Product Status	Production (NRND)	
TDK Item Descriptio	n CGA4J2X8R1H683KT5***	
Applications	Automotive Grade	<u>`</u>
Feature	AEC-Q200AEC-Q200 150°CHigh Temperature Application	
	OpenOpen Mode	
Series	CGA4(2012) [EIA 0805]	6
Brand	ТДК	В
Environmental Compliance	Image: Weight of the second	

	Size
Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	1.25mm ±0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering)
	0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering)
	0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering)
	0.90mm to 1.20mm(Reflow Soldering)

	Electrical Characteristics	
Capacitance	68nF ±10%	
Rated Voltage	50VDC	
Temperature Characteristic	X8R(±15%)	
Dissipation Factor (Max.)	3%	
Insulation Resistance (Min.)	7352ΜΩ	

Other		
Operating Temp. Range	-55 to 150°C	
Coldering Method	Wave (Flow)	
Soldering Method	Reflow	
AEC-Q200	YES	
Packing	Embossed (Plastic)Taping [180mm Reel]	
Package Quantity	2000pcs	

! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
! All specifications are subject to change without notice.

## Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)





CGA4J2X8R1H683K125AM





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CGA4J2X8R1H683K125AM

## Associated Images



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